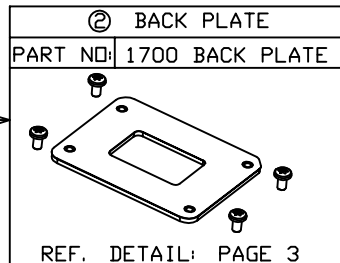
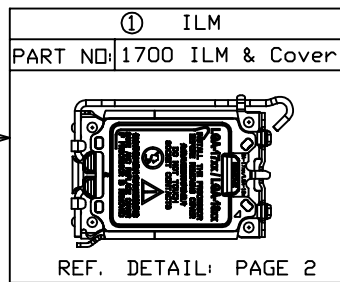
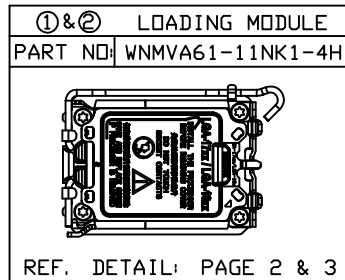
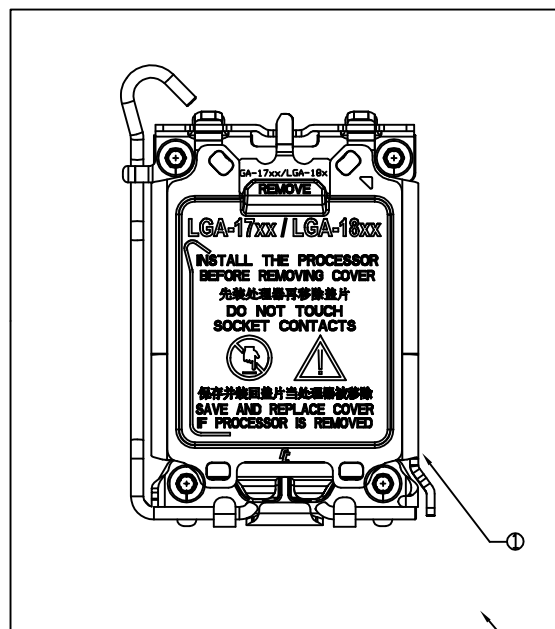


REV.	ECN. NO.	APPD.
A	BC-20-0014203	Nick Lin
B	BC-20-0030344	Nick Lin
C	BC-21-0003778	Nick Lin
D	BC-21-0005399	Nick Lin
DX1	BS-21-017149	Mac Peng

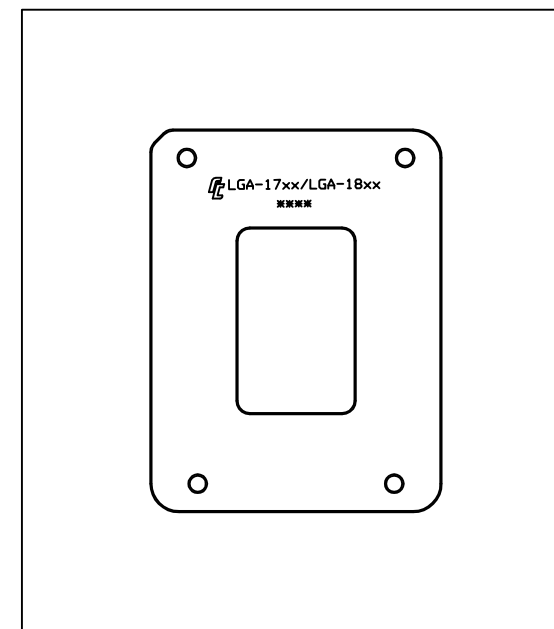




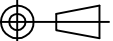
NOTES:

- ASSEMBLY PROCEDURE
 - SMT SOCKET ON BOARD BY PROPER FIXTURE & SUGGESTED PROFILE;
 - FASTEN THE ILM & BACK PLATE BY PROPER SCREW DRIVER;
 - LIFT UP LEVER TO ACTUATE LOAD PLATE FOR OPEN ILM;
 - FOLLOW THE ALIGNMENT KEY ORIENTATION TO INSERT CPU PROPERLY ;
 - ACTUATE LEVER TO CLOSE LOAD PLATE;
 - PUSH DOWN LEVER TO LOCK POSITION;
 - REMOVE PICK & PLACE DUST COVER;
 - CPU WORKS AFTER THE ABOVE PROCEDURE FINISHED.
- HARMFUL MATERIAL CONTROL PLEASE FOLLOWS DDC. NO. 'EPI12';
(COMPLIANT TO RoHS)
- PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.

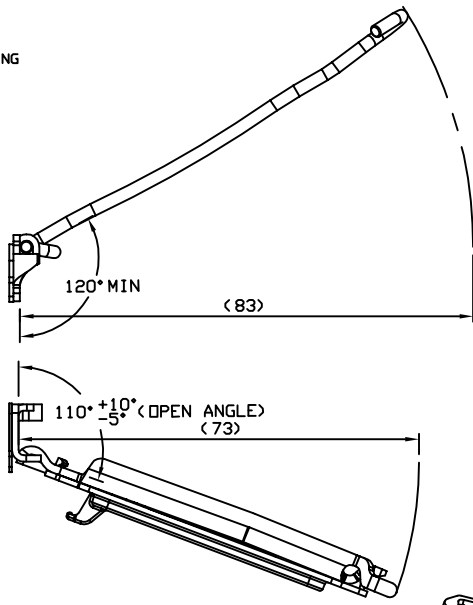
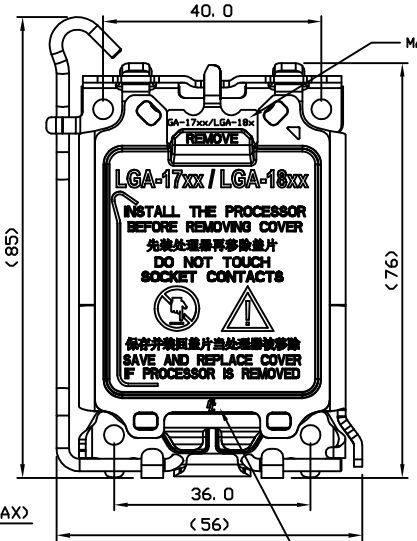


MOTHERBOARD



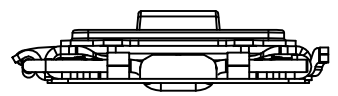
X± 0.5	X°± 1°	UNITS	mm	NAME (INTENDED USE)	 FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X± 0.2	.X°± 0.5°	MATL		SOCKET V RM DG 1.0	
.XX± 0.1	.XX°±	FINISH		QTY	PART NO. (INTENDED USE)
.XXX±	.XXX°±		WNMVA61-11NK1-4H		<input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT				APPD:	TITLE:
				Nick Lin	CUSTOMER DRAWING FOR SOCKET V RM DG 1.0
				CHKD: Mac Peng	DWG NO.: 351-0000-1562
				DR: King Ko 7/28' 21	 SCALE SHEET REV. 1: 1 1/4 DX1

< 13.5 MAX

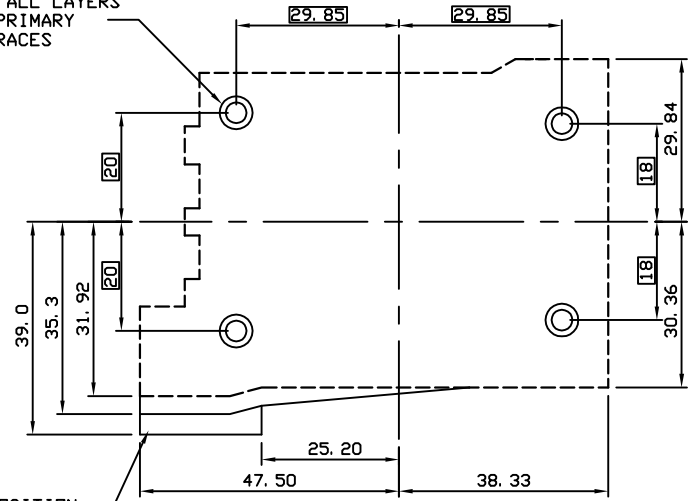


- NOTES:
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 - MATERIAL :

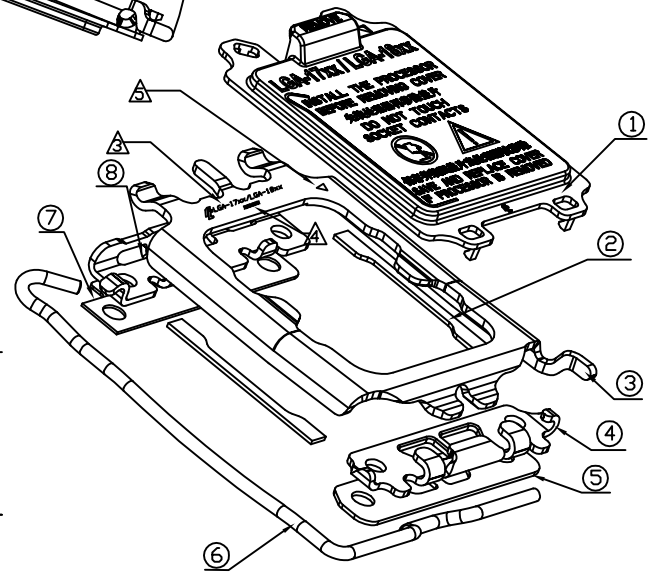
DUST COVER	PC+ABS, GREY
LOAD PLATE INSULATOR	PC, UL94VTM-0, HALOGEN FREE;
LOAD PLATE	STAINLESS STEEL;
LEVER FRAME	CARTON STEEL, NICKEL PLATED;
LEVER FRAME INSULATOR	PC, UL94VTM-0, HALOGEN FREE;
LEVER	STAINLESS STEEL;
HINGE FRAME	CARTON STEEL, NICKEL PLATED;
HINGE FRAME INSULATOR	PC, UL94VTM-0, HALOGEN FREE;
 - INTEL PART NUMBER AND FOXCONN LOGO AND MARKING ARE LOCATED APPROXIMATELY HERE;
 - DATE CODE IS LOCATED APPROXIMATELY HERE;
 - PIN 1 MARKING IS LOCATED APPROXIMATELY HERE;
 - HARMFUL MATERIAL CONTROL PLEASE FOLLOWS DDC. NO. 'EP112'; < COMPLIANT TO RoHS




4XØ4.7 NO ROUTE ON ALL LAYERS
Ø6.00 NO ROUTE ON PRIMARY SIDES FOR SIGNAL TRACES

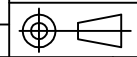


RECOMMENDED PCB KEEPOUT



COMPONENT LIST		
ITEM	DESCRIPTION	Q'TY
①	DUST COVER	1
②	LOAD PLATE INSULATOR	2
③	LOAD PLATE	1
④	LEVER FRAME	1
⑤	LEVER FRAME INSULATOR	1
⑥	LEVER	1
⑦	HINGE FRAME	1
⑧	HINGE FRAME INSULATOR	1

X± 0.5	X.°± 1°	UNITS	mm	NAME (INTENDED USE)	 FOXCONN INTERCONNECT TECHNOLOGY LIMITED.	
.X± 0.2	.X°± 0.5°	MATL		SOCKET V RM DG 1.0		
.XX± 0.1	.XX°±		③	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL	
.XXX±	.XXX°±	FINISH		APPD:	TITLE: CUSTOMER DRAWING FOR SOCKET V RM DG 1.0	
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					CHKD: Mac Peng	SCALE SHEET REV.
					DR: King Ko 7/28' 21	1: 1 2/4 DX1



IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

REV. ECN. NO. APPD.

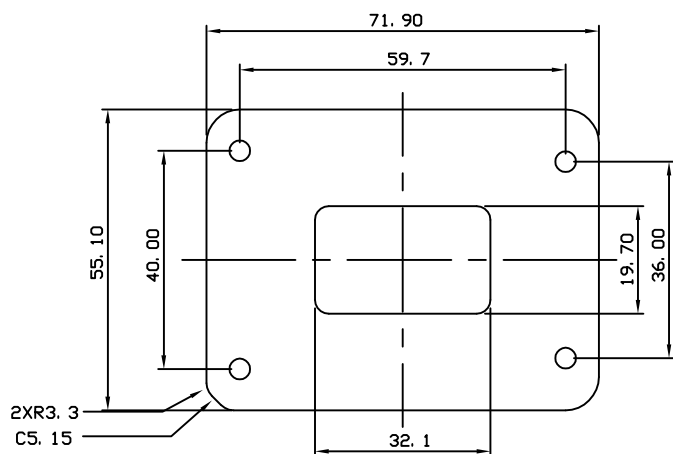
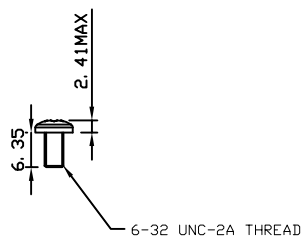
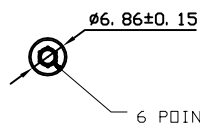
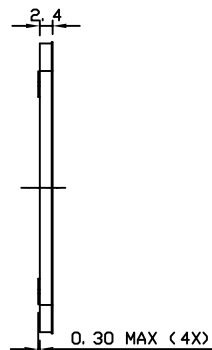
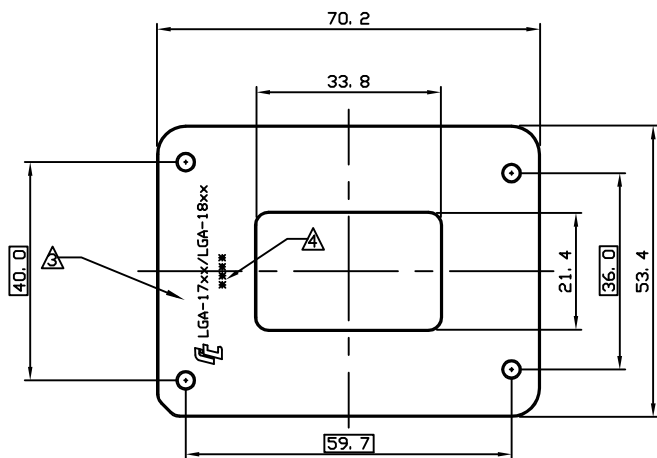
ATTACH ADHESIVE BACKED INSULATOR TO THE BACK PLATE

NOTES:

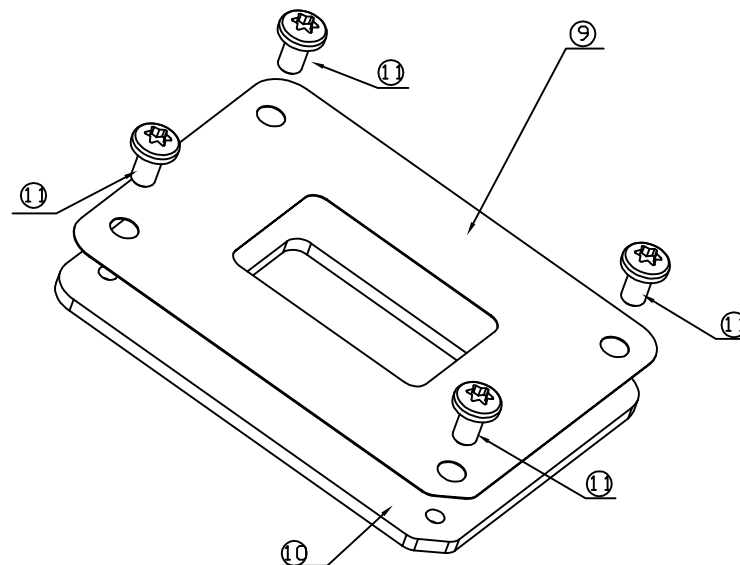
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- MATERIAL: BACK PLATE INSULATOR PC, UL94VTM-0, HALOGEN FREE; BACK PLATE CARTON STEEL, NICKEL PLATED; SCREW LOW CARBON STEEL;
- INTEL PART NUMBER AND FOXCONN LOGO AND MARKING ARE LOCATED APPROXIMATELY HERE;
- DATE CODE IS LOCATED APPROXIMATELY HERE;
- HARMFUL MATERIAL CONTROL PLEASE FOLLOWS DOC. NO. 'EPI12'; (COMPLIANT TO RoHS)



COMPONENT LIST

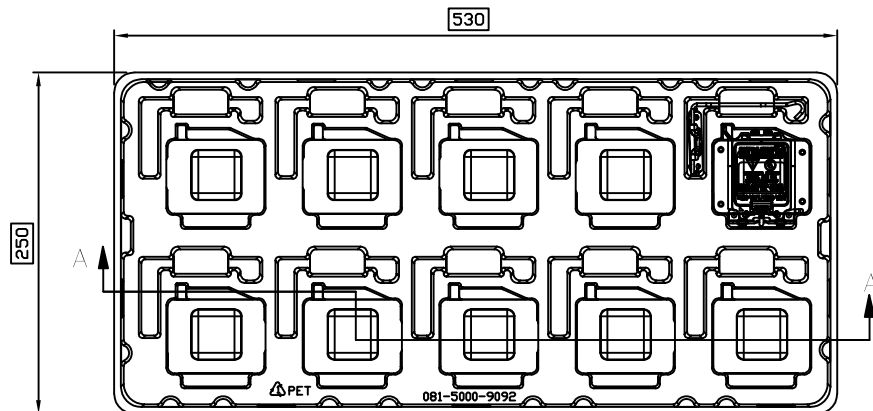
ITEM	DESCRIPTION	Q'TY
⑨	BACK PLATE INSULATOR	1
⑩	BACK PLATE	1
⑪	SCREW	4



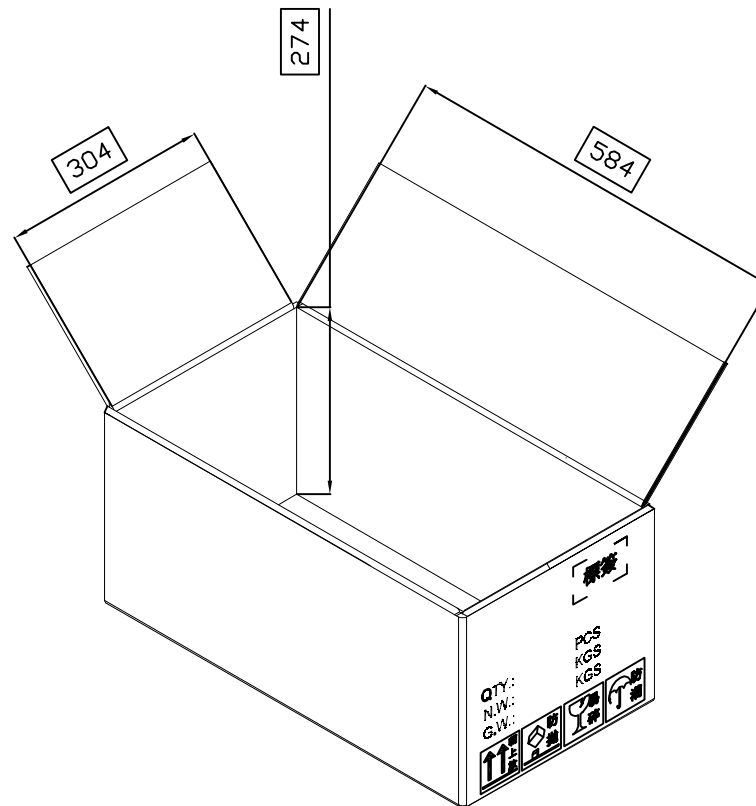
RECOMMENDED PCB BOTTOM SIDE KEEP OUT ZONE



X± 0.5	X°± 1°	UNITS	mm	NAME (INTENDED USE)	 FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X± 0.2	.X°± 0.5°	MAT'L		SOCKET V RM DG 1.0	
.XX± 0.1	.XX°±	FINISH		APPD:	PART NO. (INTENDED USE) WNMVA61-11NK1-4H
.XXX±	.XXX°±	Q'TY	DR:	Nick Lin Mac Peng King Ko 7/28'21	TITLE: CUSTOMER DRAWING FOR SOCKET V RM DG 1.0 DWG NO.: 351-0000-1562
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				REV. DX1	





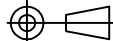
SECTION : A-A



DETAIL B

SCALE 1 : 8

NOTES : 10PCS/TRAY , 100PCS/CARTON .

X± 0.5	X°± 1°	UNITS	mm	NAME(INTENDED USE)	 FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X± 0.2	.X°± 0.5°	MAT'L		SOCKET V RM DG 1.0	
.XX± 0.1	.XX°±	FINISH		Q'TY	PART NO.(INTENDED USE)
.XXX±	.XXX°±		APPD:		Nick Lin
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.				CHKD: Mac Peng	TITLE: CUSTOMER DRAWING FOR SOCKET V RM DG 1.0
				DR: King Ko 7/24' 21	DWG NO.: 351-0000-1562
				 SCALE 1:4	SHEET 4/4